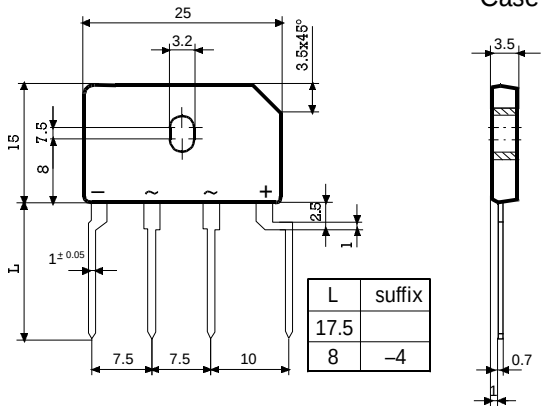


5 Amp. Glass Passivated Bridge Rectifier

Dimensions in mm.  Plastic Case • Mounting Instructions • High temperature soldering guaranteed: 260 °C – 10 sc. • Recommended mounting torque: 8 Kg.cm.	Voltage 100 to 1000 V. Current 5.0 A. HYPERECTIFIER®
	• Glass Passivated Junction Chips. • UL recognized under component index file number E130180. • Lead and polarity identifications. • Case: Molded Plastic. • Ideal for printed circuit board (P.C.B.). • High surge current capability. • The plastic material carries U/L recognition 94 V-O.

Maximum Ratings, according to IEC publication No. 134

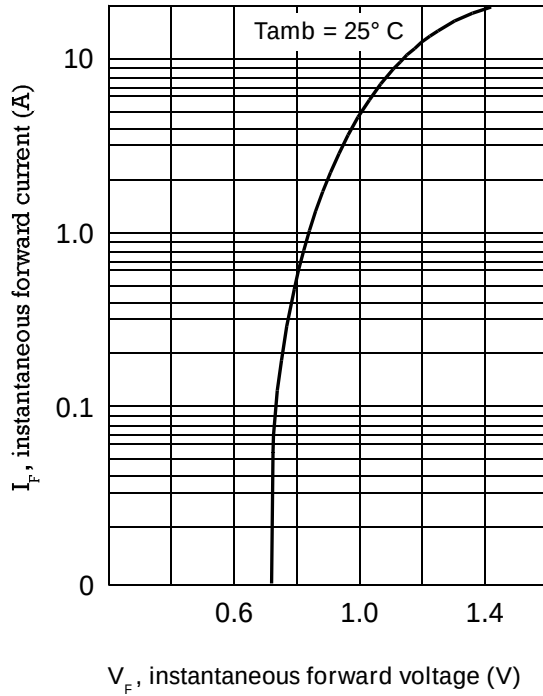
		FBI5B 1M1	FBI5D 1M1	FBI5F 1M1	FBI5J 1M1	FBI5L 1M1	FBI5M 1M1
V_{RRM}	Peak Recurrent Reverse Voltage (V)	100	200	300	600	900	1000
V_{RMS}	Maximum RMS Voltage (V)	70	140	210	420	630	700
V_R	Recommended Input Voltage (V)	40	80	125	250	380	500
$I_{F(AV)}$	Max. Average forward current with heatsink without heatsink	5.0 A at 100 °C 3.0 A at 25 °C					
I_{FRM}	Recurrent peak forward current	30 A					
I_{FSM}	10 ms. peak forward surge current	250 A					
I^2t	I^2t value for fusing (t = 10 ms)	300 A ² sec					
V_{DIS}	Dielectric strength (terminals to case, AC 1 min.)	1500 V					
T_j	Operating temperature range	– 40 to + 150 °C					
T_{stg}	Storage temperature range	– 40 to +150 °C					

Electrical Characteristics at Tamb = 25°C

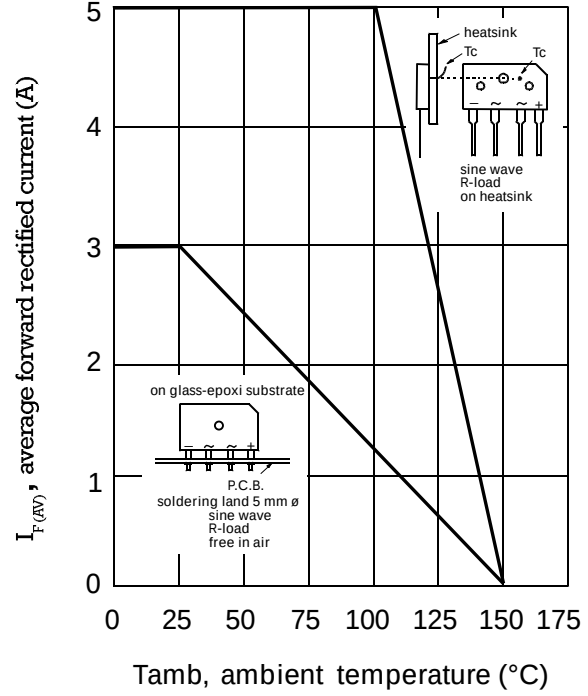
V_F	Max. forward voltage drop per element at $I_F = 5$ A	1.1 V
I_R	Max. reverse current per element at V_{RRM}	5 μ A
$R_{th(j-c)}$ $R_{th(j-a)}$	MAXIMUM THERMAL RESISTANCE Junction-Case. With Heatsink. Junction-Ambient. Without Heatsink.	2.2 °C/W 22 °C/W

Characteristic Curves

TYPICAL FORWARD CHARACTERISTIC



FORWARD CURRENT DERATING CURVE



MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

